



irfu



T. Lécresse



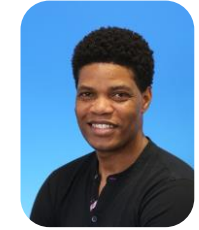
C. Genot



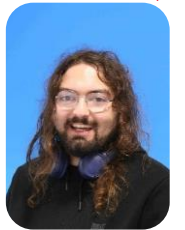
E. Benoist



G. Lenoir



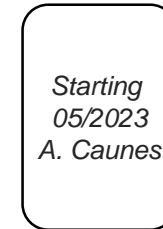
E. Pepinter



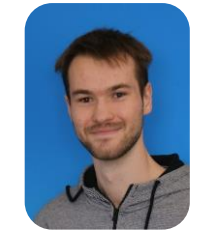
T. Barabe



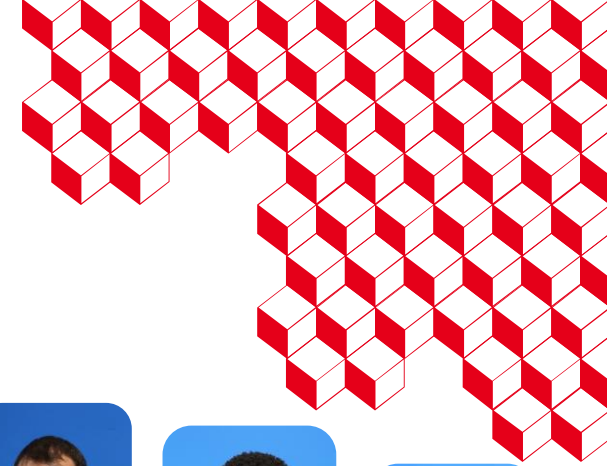
R. Correia-Machado



*Starting
05/2023
A. Caunes*



A. Blondelle



Introduction to the activities of the WP2.11 – at CEA

CEA-CERN HFM collaboration agreements (KE5647)

T. Lécresse , C. Genot

+ help of P. Fazilleau, N. Jerance...

OUTLINE

1

- Introduction to KE5647 agreement Toward 16+ T HTS dipole magnet

2

- Scope of the project

3

- Electromagnetic and thermal modeling

4

- Mechanical model

5

- Conceptual model and technological developments

6

- Thermal measurements

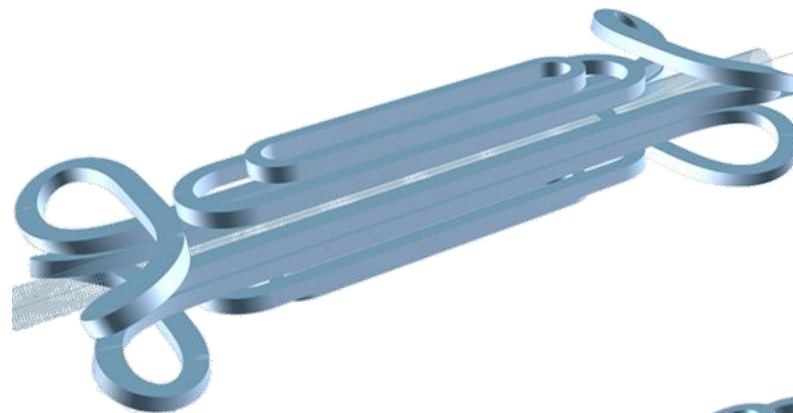
1. Introduction to KE5647 agreement Toward 16+ T HTS dipole magnet



Global roadmap phases

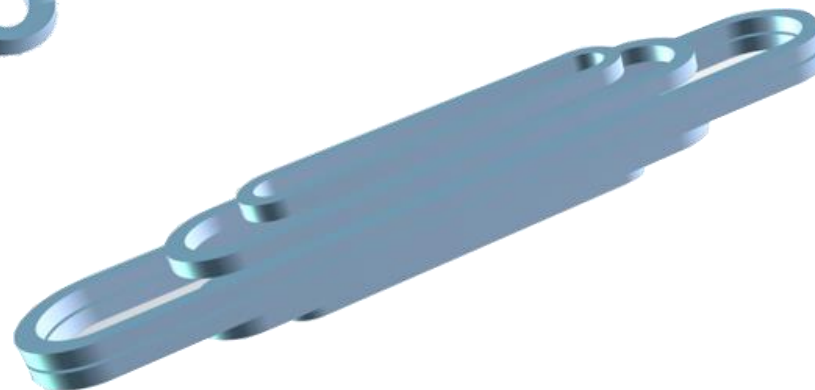
Phase 3 :

« EuCARD V3 »
MI cold bore 16 T+
magnet



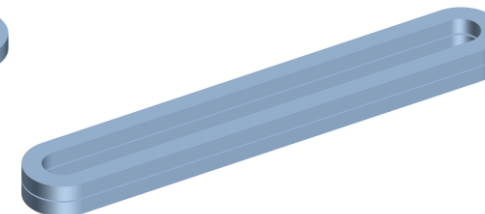
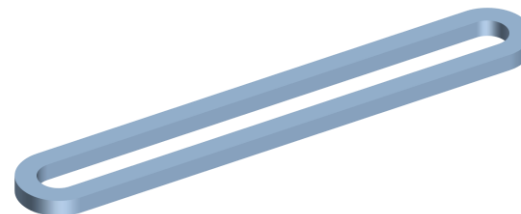
Aperture +
Field quality measurements

Phase 2 :
magnet MI 16 T+
« EuCARD V2 »



Mechanics + high field +
Quench + assembly

Phase 1 (KE5647) 2023-2025:
Simple or double Racetrack MI



Models + techno

1. Introduction to KE5647 agreement Toward 16+ T HTS dipole magnet

Philosophy

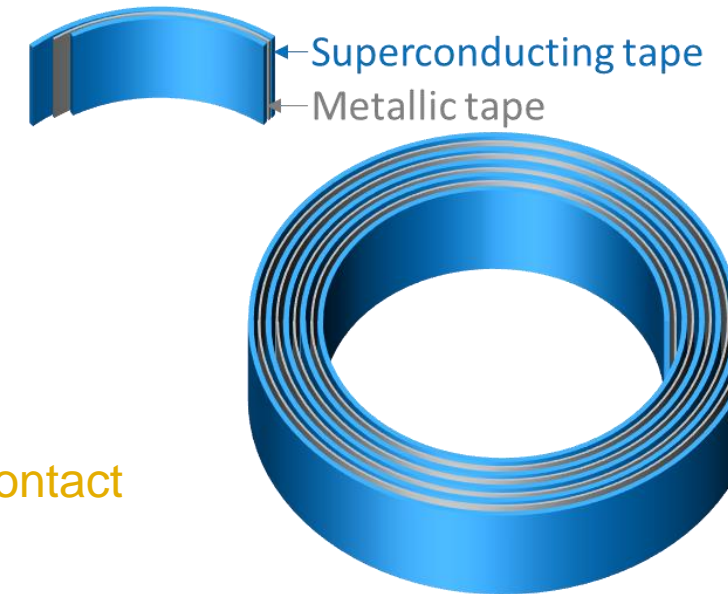
➤ Feedback from previous programs

- HTS cables : Field quality / stability BUT Cost / supply / modeling
- Insert : High Field with limited conductor BUT OD limit / higher risk / specific test station
- Metal as Insulation (MI) technology on solenoids
 - Hot spot protection BUT mechanics problem are possible
 - Good charging BUT losses to consider + transient field quality
 - Good steady state field BUT transient more complexe
 - R_{ct} tuning



➤ Applying MI technology to racetrack bloc dipole magnet

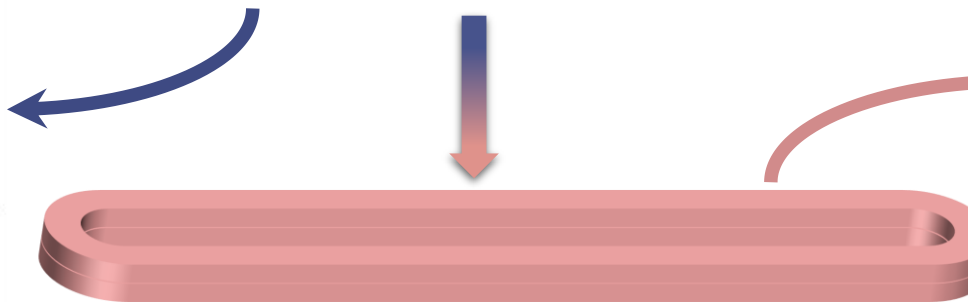
- Racetrack bloc magnet experience BUT need reliable turn-to-turn contact
- Tape based winding
- Evaluate the magnet without hotspot risk in case of quench



2. Scope of the project

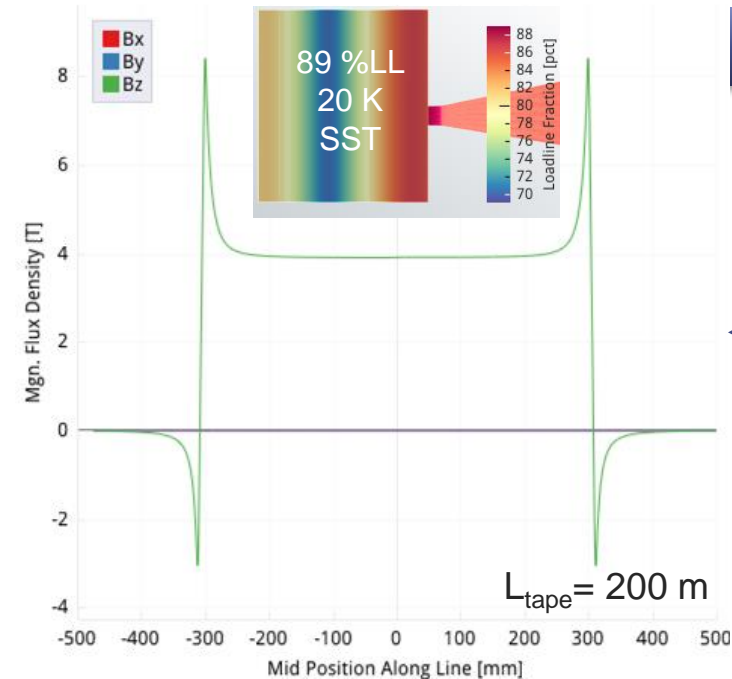
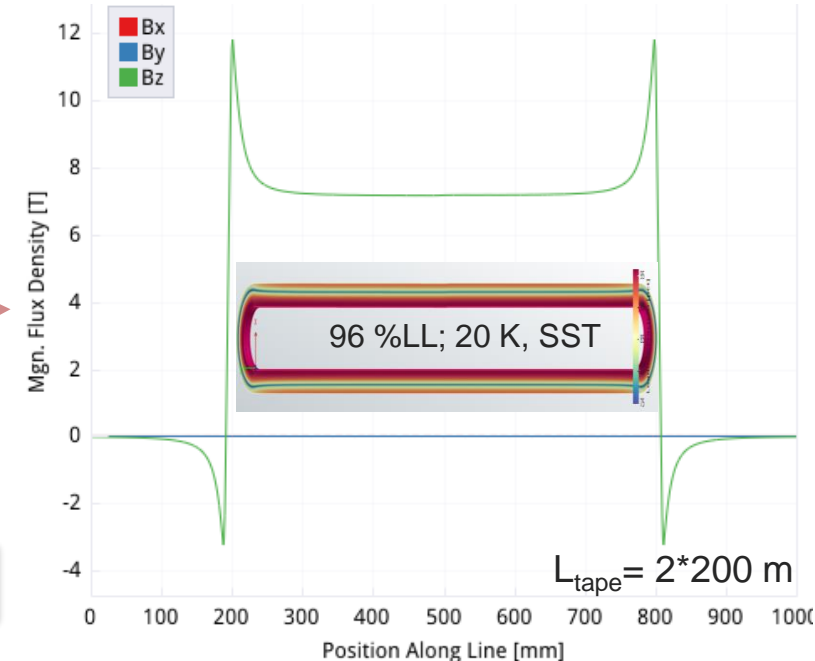
Design and fabricate a MI racetrack coil

Option 1 2000 A, 1 HTS tape, MI



2000 A, 1 HTS tape, MI

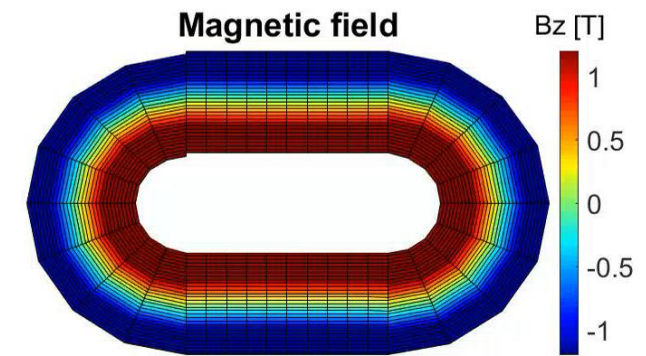
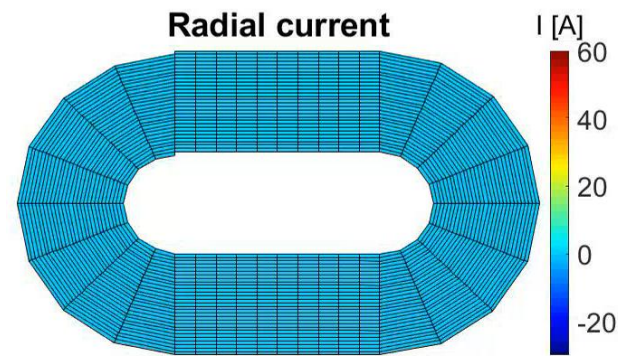
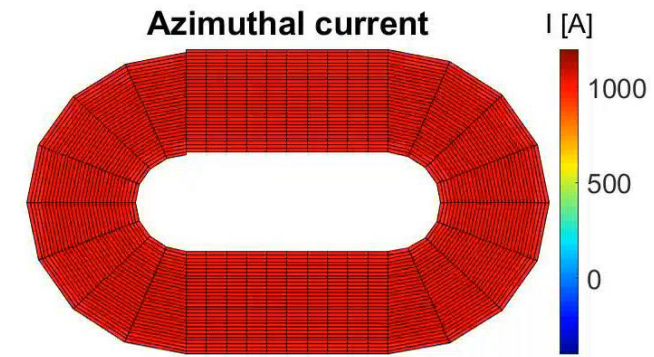
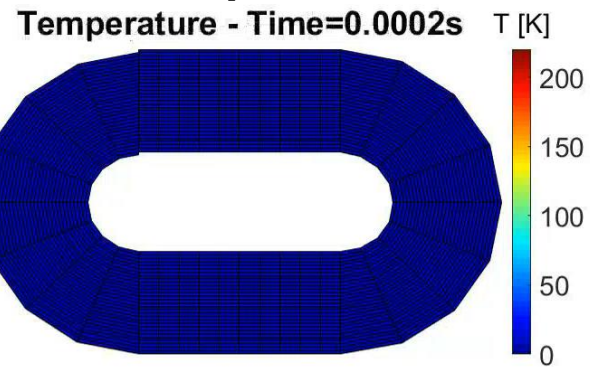
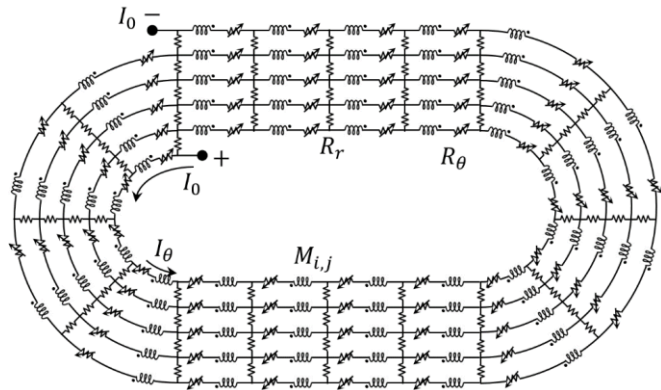
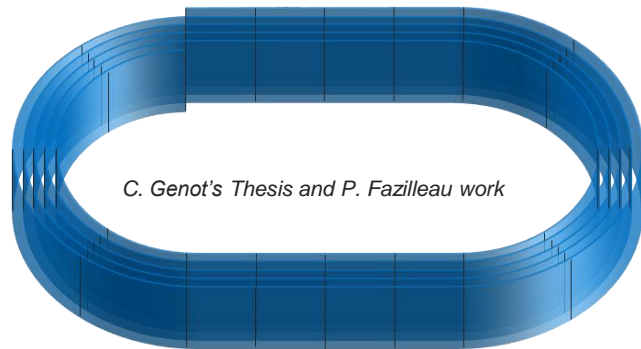
Option 2



- **Electromagnetic MI model** (Existing PEEC model + updates –induced currents, optimization for faster simulation-)
- **Mechanical model** (CASTEM, ANSYS)
- **Conceptual and technological development** works (Structure, Winding, Electrical connection...)
- **Cryogenics and thermal model** (thermal properties measurements, evaluate the cryogen free solution)
- **Test station** (interfaces and thermal links)

3. Electromagnetic and thermal modeling

CEA PEEC model (initial development for solenoids)



- Parametric study (R_{ct} , k_r , coil length, turn to turn pressure...)
- Implement a multi-racetrack model
- Include magnetization (possibility under consideration)
- Optimize the codes for large coils → effective protection methods → local temperature, energy extraction, protection scheme...



Not to scale: $ID = 100$ mm ; $L = 200$ mm

A. Blondelle and C. Genot with support of P. Fazilleau and N. Jerance

4. Mechanical model (CASTEM, ANSYS)

From EuCARD (5.4 T at 4.2 K) magnet studies : Feedback and optimization

Previous models and experimental tests

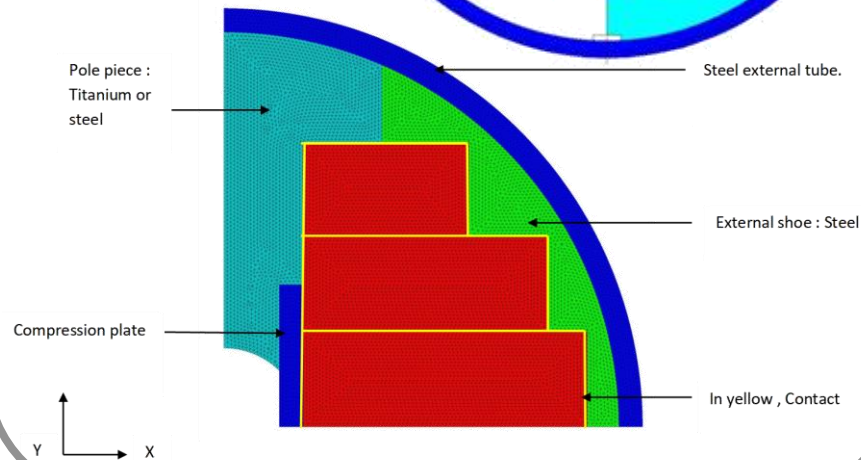
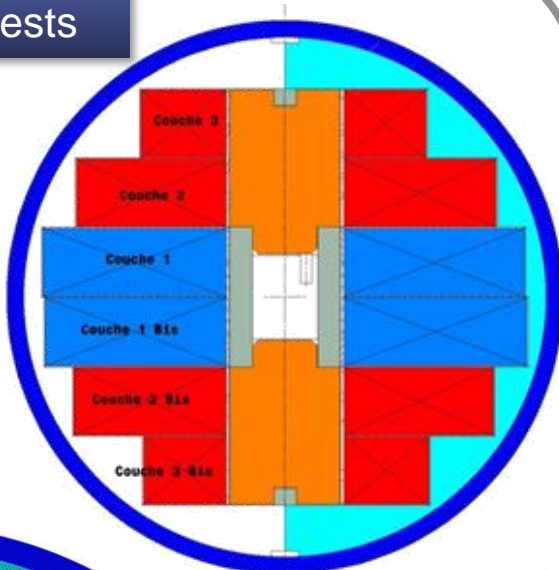
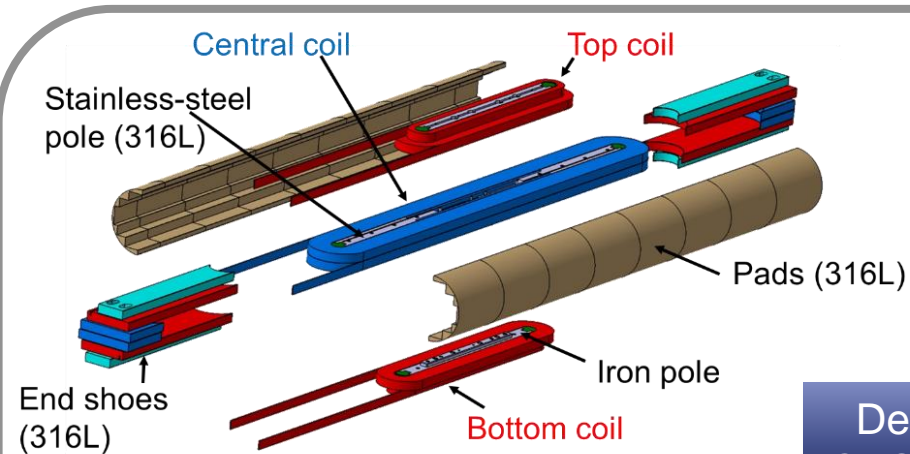


Figure 1 : Meshed model



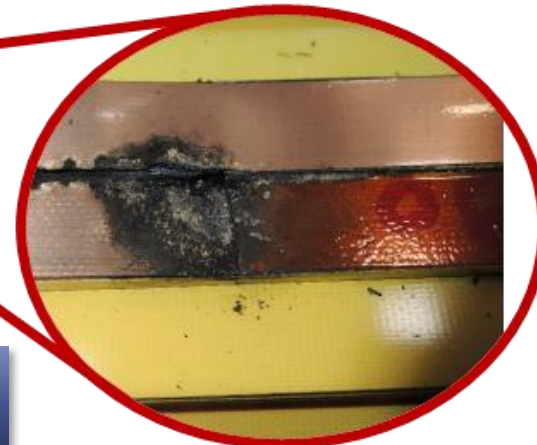
Glass epoxy inter-coil and external insulation

Developments with CASTEM and ANSYS

Mechanics around leads + insulation ?

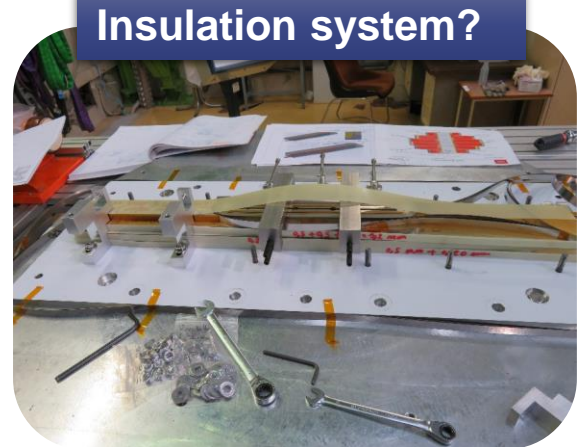
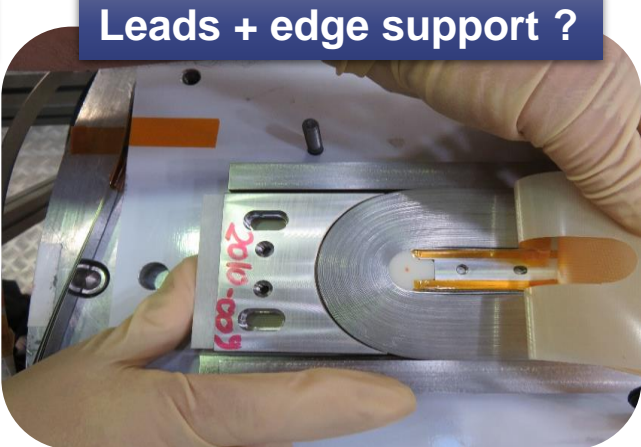
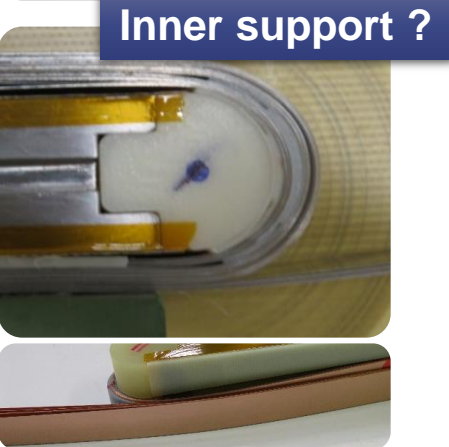
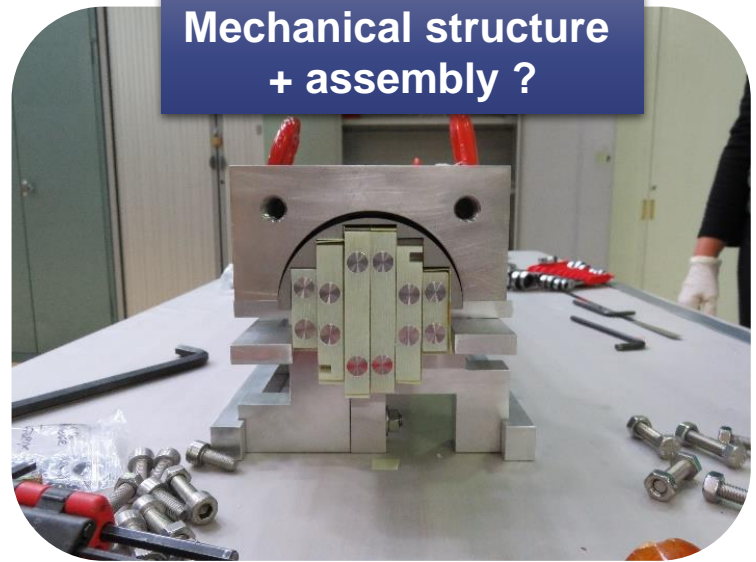
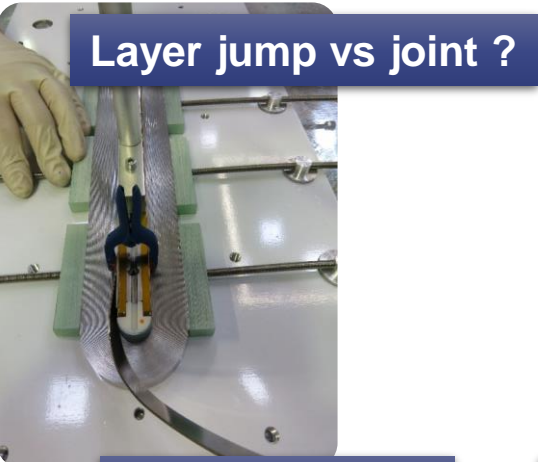
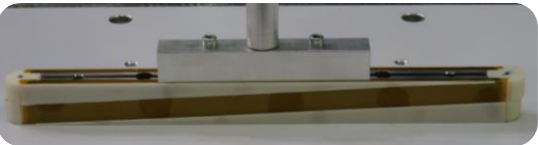


Local stress with non-impregnated coil



5. Conceptual model and technological developments

From EuCARD (5.4 T at 4.2 K) magnet studies : Feedback and optimization



Smooth Winding of cowound tapes ?

Mechanical structure + assembly ?

Layer jump vs joint ?

Inner support ?

Leads + edge support ?

Insulation system?

- Racetrack vs double racetrack
- Insulation scheme
- Current injection + internal joints
- Dry winding vs impregnation
- Smooth winding with thin tapes
- ...

6. Thermal measurements

Transverse thermal conductivity measurement (k_r) versus temperature and pressure

PEEC model : thermal equations

$$\rho C_p \frac{\partial T}{\partial t} = \text{div}(k\nabla T) + S \rightarrow \rho C_p \frac{\partial T}{\partial t} = \frac{k_r}{r} \frac{\partial T}{\partial r} + k_r \frac{\partial^2 T}{\partial r^2} + \frac{k_\theta}{r^2} \frac{\partial^2 T}{\partial \theta^2} + S$$

Existing test station (MECTIX)
(development through previous collaboration)

Example Nb_3Sn
10 stack sample

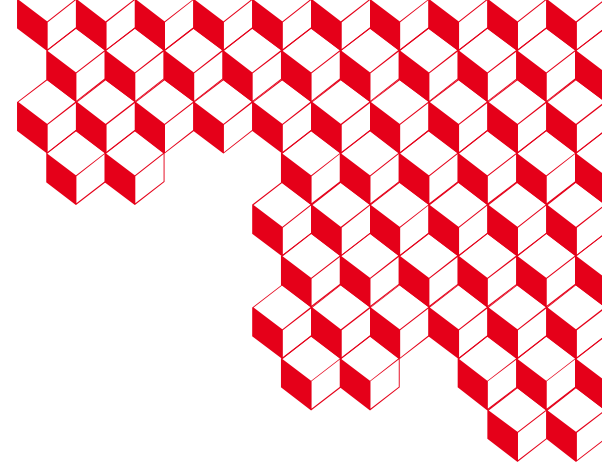
Need a specific sample for HTS MI

Stack: 12 x 40 x 2 mm

- Pressure uniformity (ANSYS model)
- Pressure study up to 100 MPa
- 5 samples to be made (time/cost driven)
- **First sample structure procurement ongoing**



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Thank you



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